



DGD0504

HALF-BRIDGE GATE DRIVER IN W-DFN3030-10 (Type TH)

Description

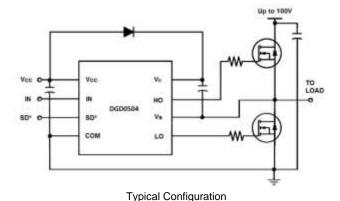
The DGD0504 is a high-voltage, high-speed gate driver capable of driving N-channel MOSFETs and IGBTs in a half-bridge configuration. High-voltage processing techniques enable the DGD0504's high-side to switch to 100V in a bootstrap operation.

The DGD0504 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver outputs feature high-pulse current buffers designed for minimum driver cross conduction. DGD0504 has a fixed internal deadtime of 430ns (typical).

The DGD0504 is offered in the W-DFN3030-10 (Type TH) package and operates over an extended -40°C to +125°C temperature range.

Applications

- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers

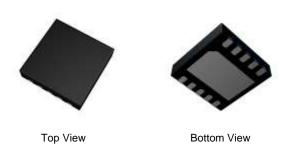


Features

- Floating High-Side Driver in Bootstrap Operation to 100V
- Drives Two N-Channel MOSFETs or IGBTs in a Half-Bridge Configuration
- 290mA Source/600mA Sink Output Current Capability
- Outputs Tolerant to Negative Transients
- Internal Dead Time of 430ns to Protect MOSFETs
- Wide Low-Side Gate Driver Supply Voltage: 10V to 20V
- Logic Input (IN and SD*) 3.3V Capability
- Schmitt Triggered Logic Inputs
- Undervoltage Lockout for V_{CC} (Logic and Low Side Supply)
- Extended Temperature Range: -40°C to +125°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony free. "Green" Device (Note 3)

Mechanical Data

- Case: W-DFN3030-10 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Finish
 Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.017 grams (Approximate)



W-DFN3030-10 (Type TH)

Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
DGD0504FN-7	DGD0504	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

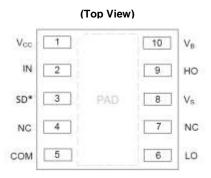
Marking Information



DGD0504 = Product Type Marking Code YY = Year (ex: 17 = 2017) WW = Week (01 to 53)



Pin Diagrams

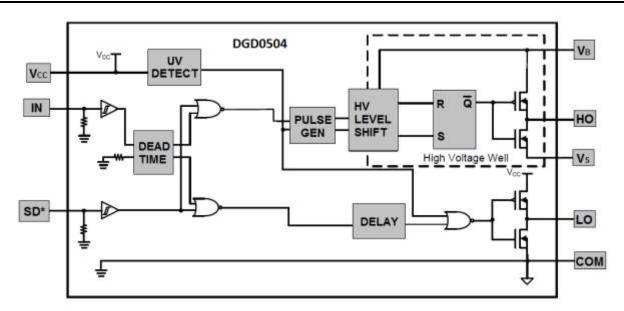


W-DFN3030-10 (Type TH)

Pin Descriptions

Pin Number	Pin Name	Function
1	Vcc	Logic and Low-Side Supply
2	IN	Logic Input for High-Side and Low-Side Gate Driver Outputs (HO and LO), in Phase with HO
3	SD*	Logic Input for Shutdown, Enabled Low
4, 7	NC	No Connection (No Internal Connection)
5	COM	Low-Side and Logic Return
6	LO	Low-Side Gate Drive Output
8	Vs	High-Side Floating Supply Return
9	НО	High-Side Gate Drive Output
10	V _B	High-Side Floating Supply
PAD	Substrate	Connect to COM on PCB

Functional Block Diagram





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-Side Floating Supply Voltage	V _B	-0.3 to +124	V
High-Side Floating Supply Offset Voltage	Vs	V _B -24 to V _B +0.3	V
High-Side Floating Output Voltage	V _{HO}	V_S -0.3 to V_B +0.3	V
Offset Supply Voltage Transient	dV _S /dt	50	V/ns
Low-Side Fixed Supply Voltage	V _{CC}	-0.3 to +24	V
Low-Side Output Voltage	V_{LO}	-0.3 to V _{CC} +0.3	V
Logic Input Voltage (IN and SD*)	V _{IN}	-0.3 to V _{CC} +0.3	V

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation Linear Derating Factor (Note 5)	P_{D}	0.4	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ heta JA}$	64	°C/W
Thermal Resistance, Junction to Case (Note 5)	$R_{ heta JC}$	42	°C/W
Operating Temperature	T_J	+150	
Lead Temperature (Soldering, 10s)	T _L	+300	°C
Storage Temperature Range	T _{STG}	-55 to +150	

Note:

5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High Side Floating Supply Absolute Voltage	V_{B}	V _S + 10	V _S + 20	V
High Side Floating Supply Offset Voltage	Vs	(Note 6)	100	V
High Side Floating Output Voltage	V _{HO}	Vs	V _B	V
Low Side Fixed Supply Voltage	Vcc	10	20	V
Low Side Output Voltage	V_{LO}	0	V _{CC}	V
Logic Input Voltage (IN and SD*)	V _{IN}	0	5	V
Ambient Temperature	T _A	-40	+125	°C

Note:

6. Logic operation for V_S of -5V to +100V. Logic state held for V_S of -5V to -V_{BS}.



$\textbf{DC Electrical Characteristics} \ (V_{BIAS} \ (V_{CC}, V_{BS}) = 15 V, \ @T_A = +25 ^{\circ}C, \ unless \ otherwise \ specified.) \ (Note \ 7)$

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Logic "1" (IN) & Logic "0" (SD*) Input Voltage	V _{IH}	2.5	_	_	V	V _{CC} = 10V to 20V
Logic "0" (IN) & Logic "1" (SD*) Input Voltage	VIL	_	_	0.8	V	V _{CC} = 10V to 20V
High Level Output Voltage, V _{BIAS} - V _O	VoH	_	0.05	0.2	V	$I_0 = 2mA$
Low Level Output Voltage, V _O	V _{OL}	_	0.02	0.1	V	$I_0 = 2mA$
Offset Supply Leakage Current	I _{LK}	_	_	50	μA	$V_B = V_S = 100V$
Quiescent V _{BS} Supply Current	I _{BSQ}	_	60	100	μA	V _{IN} = 0V or 5V
Quiescent V _{CC} Supply Current	Iccq	_	350	500	μA	V _{IN} = 0V or 5V
Logic "1" Input Bias Current	I _{IN+}	_	3.0	10	μA	$V_{IN} = 5V, SD^* = 0V$
Logic "0" Input Bias Current	I _{IN-}	_	_	5.0	μA	$V_{IN} = 0V, SD^* = 5V$
V _{CC} Supply Undervoltage Positive Going Threshold	V _{CCUV+}	7.4	8.5	9.6	V	_
V _{CC} Supply Undervoltage Negative Going Threshold	Vccuv-	7.1	7.8	8.8	V	_
V _{BS} Supply Undervoltage Positive Going Threshold	V _{BSUV+}	5.5	6.5	7.5	V	_
V _{BS} Supply Undervoltage Negative Going Threshold	V _{BSUV} -	5.3	6.3	7.3	V	_
Output High Short Circuit Pulsed Current	I _{O+}	130	290	_	mA	V _O = 0V, PW ≤ 10μs
Output Low Short Circuit Pulsed Current	l ₀₋	270	600	_	mA	V _O = 15V, PW ≤ 10μs

Note:

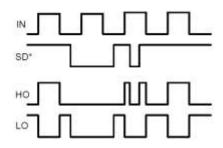
AC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, C_L = 1,000pF, @ T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Turn-On Propagation Delay	ton	_	680	820	ns	V _S = 0V
Turn-Off Propagation Delay	t _{OFF}	_	150	220	ns	V _S = 100V
Shutdown Propagation Delay	t _{SD}	_	160	220	ns	_
Delay Matching, HO and LO Turn-On/Turn-Off	t _{DM}	_	_	60	ns	_
Turn-On Rise Time	t _R	_	70	170	ns	V _S = 0V
Turn-Off Fall Time	t _F	_	35	90	ns	V _S = 0V
Deadtime: t _{DT LO-HO} & t _{DT HO-LO}	t _{DT}	300	430	550	ns	_

^{7.} The V_{IN} and I_{IN} parameters are applicable to the two logic pins: IN and SD*. The V_{O} and I_{O} parameters are applicable to the respective output pins: HO and LO.



Timing Waveforms





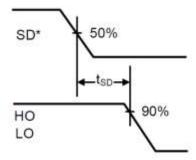


Figure 2. Shutdown Waveform Definition

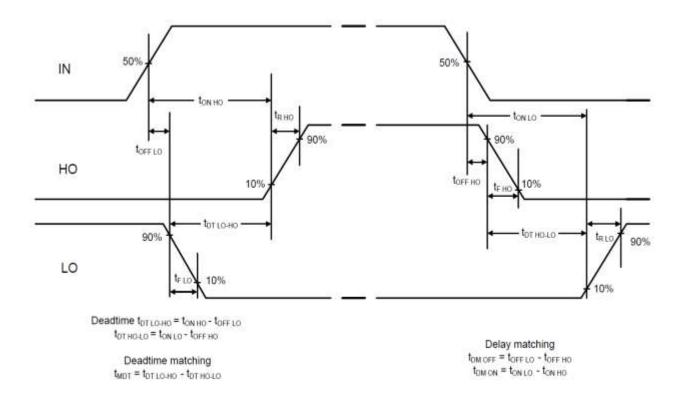


Figure 3. Switching Time Waveform Definitions



Typical Performance Characteristics (@T_A = +25°C, unless otherwise specified.)

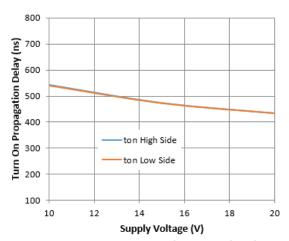


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

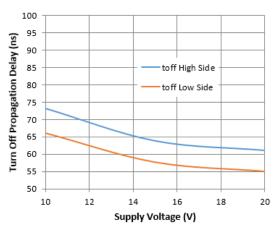


Figure 6. Turn-off Propagation Delay vs. Supply Voltage

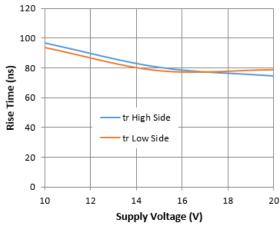


Figure 8. Rise Time vs. Supply Voltage

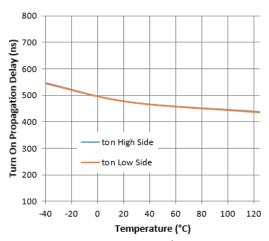


Figure 5. Turn-on Propagation Delay vs. Temperature

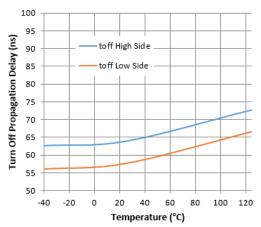


Figure 7. Turn-off Propagation Delay vs. Temperature

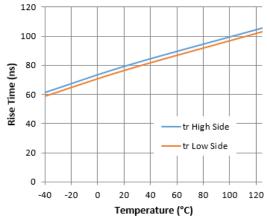


Figure 9. Rise Time vs. Temperature



Typical Performance Characteristics (Continued)

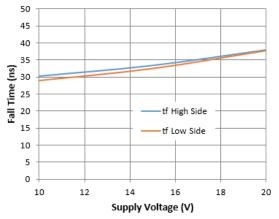


Figure 10. Fall Time vs. Supply Voltage

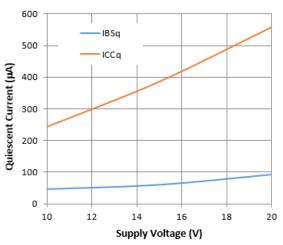


Figure 12. Quiescent Current vs. Supply Voltage

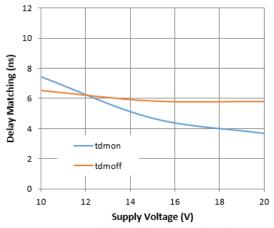


Figure 14. Delay Matching vs. Supply Voltage

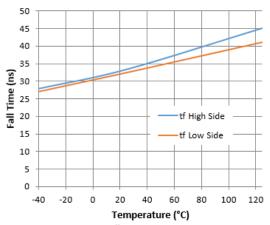


Figure 11. Fall Time vs. Temperature

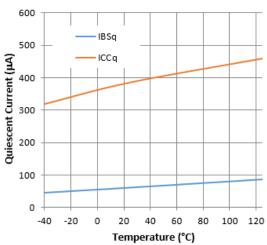


Figure 13. Quiescent Current vs. Temperature

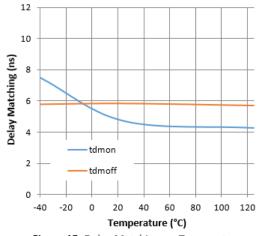


Figure 15. Delay Matching vs. Temperature



Typical Performance Characteristics (Cont.)

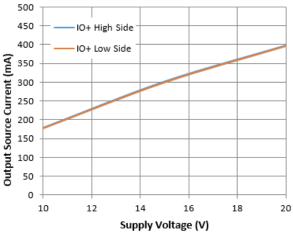


Figure 16. Output Source Current vs. Supply Voltage

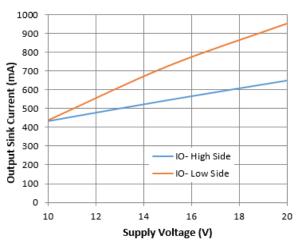


Figure 18. Output Sink Current vs. Supply Voltage

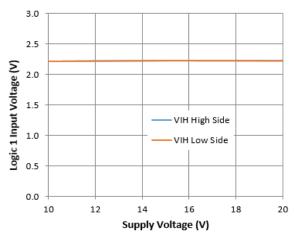


Figure 20. Logic 1 Input Voltage vs. Supply Voltage

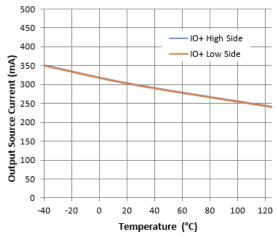


Figure 17. Output Source Current vs. Temperature

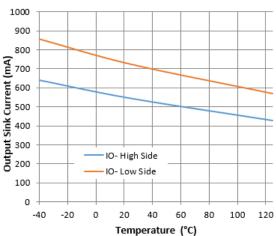


Figure 19. Output Sink Current vs. Temperature

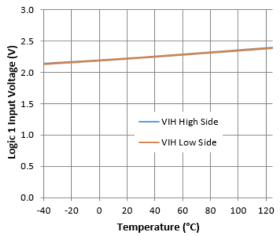


Figure 21. Logic 1 Input Voltage vs. Temperature



Typical Performance Characteristics (Cont.)

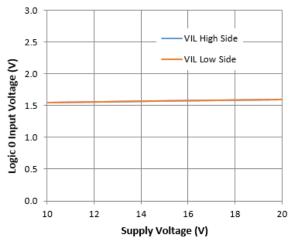


Figure 22. Logic O Input Voltage vs. Supply Voltage

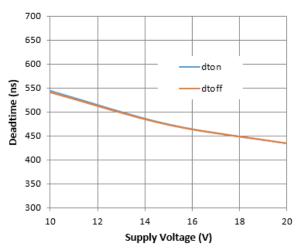


Figure 24. Deadtime vs. Supply Voltage

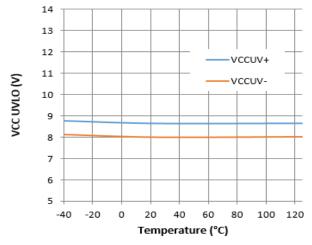


Figure 26. VCC UVLO vs. Temperature

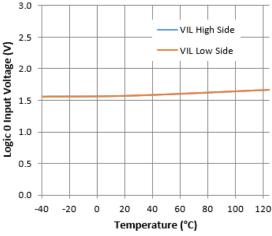


Figure 23. Logic 0 Input Voltage vs. Temperature

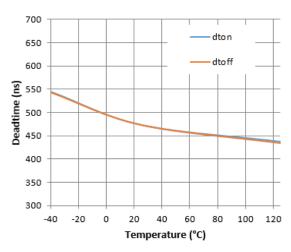


Figure 25. Deadtime vs. Temperature

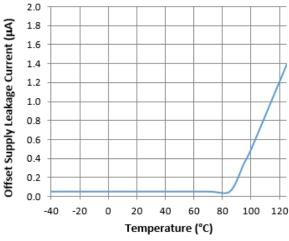


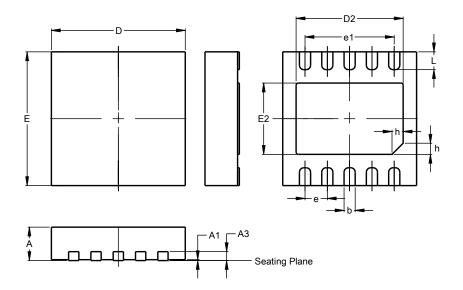
Figure 27. Offset Supply Leakage Current vs. Temperature



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

W-DFN3030-10 (Type TH)

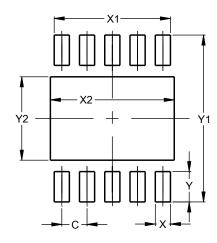


	W-DFN3030-10					
(Type TH)						
Dim	Min	Max	Тур			
Α	0.70	0.80	0.75			
A1	-	0.05	0.02			
A3	0.18	0.25	0.20			
b	0.18	0.30	0.25			
D	2.90	3.10	3.00			
D2	2.40	2.60	2.50			
е	0.50BSC					
e1	2.00BSC					
E	2.90	3.10	3.00			
E2	1.45	1.65	1.55			
h	0.20	0.30	0.25			
L	0.30	0.50	0.40			
All	All Dimensions in mm					

Suggested Pad Layout

 $\label{prop:lease} Please see \ http://www.diodes.com/package-outlines.html for the latest version.$

W-DFN3030-10 (Type TH)



Dimensions	Value (in mm)
С	0.500
X	0.300
X1	2.300
X2	2.600
Y	0.600
Y1	3.300
Y2	1.650

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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